

## Claims

1. A method of assembling a packaged high frequency circuit module including the steps of :
  - 5 providing a ceramic substrate having one or more elongate stub walls projecting from a planar surface thereof;  
firing the ceramic substrate;  
processing the surface of the substrate until the planar surfaces of the elongate stub walls are uniform and parallel;
  - 10 applying a conductive adhesive to the processed surfaces of the stub walls;  
placing a housing lid over the substrate, the lid having one or more members projecting from a planar surface thereof so that the members align with the stub walls of the substrate to form a composite structure
- 15 2. A method according to claim 1, wherein the stub walls extend, at least partially, around the periphery of the planar surface of the substrate.
3. A method according to claims 1 or 2, wherein one or more stub walls project from the internal surface of the substrate
4. A method according to any preceding claim, wherein the projection of the  
20 stub walls from the planar surface of the substrate is proportional to predetermined surface distortion values for such a substrate.
5. A method according to any preceding claim wherein processing the surface comprises one or more of grinding, lapping or polishing the surface.
- 25 6. A method according to claim 1, further comprising the steps of  
applying pressure to the composite structure and curing the conductive adhesive.

7. A method according to claim 1, wherein the elongate stub walls project from the upper planar surface of the substrate.
8. A method according to claim 1, wherein the elongate stub walls project from the lower planar surface of the substrate.
- 5 9. A high frequency circuit module comprising:
  - a ceramic substrate having one or more elongate stub walls projecting from a planar surface thereof, the planar surfaces of the stub walls having been processed so that they are uniform and parallel;
  - a conductive adhesive layer on the processed surfaces of the stub walls;
  - 10 and
  - a housing lid mounted over the substrate, the lid having one or more members projecting from a planar surface thereof so that the members align with the stub walls of the substrate to form a composite structure.